




## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-11-30
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement			
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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L6229QTR	8N42*UR38BA6	A	Z7GA	2015-11-30
Amount		UoM	Unit type	ST ECOPACK Grade
69.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	5x5x1	32	gull wing	
Comment	Package: VFQFPN 5X5x1.0 32L PITCH 0.5			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8N42*UR38BA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	7.156	mg	supplier	die	Silicon (Si)	7440-21-3		6.801	mg	950391	98565
				supplier	metallization	Aluminium (Al)	7429-90-5		0.069	mg	9642	1000
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	1118	116
				supplier	Passivation	Silicon Nitride	12033-89-5		0.020	mg	2795	290
				supplier	Passivation	Silicon Oxide	7631-86-9		0.119	mg	16629	1725
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.005	mg	699	72
				supplier	back side metallization	Gold (Au)	7440-57-5		0.014	mg	1956	203
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.046	mg	6428	667
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.074	mg	10341	1072
				Leadframe	Copper & Its alloys	18.436	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.409	mg	22185	5928
supplier	alloy	Phosphorus (P)	12185-10-3						0.006	mg	325	87
supplier	alloy	Zinc (Zn)	7440-66-6						0.025	mg	1356	362
supplier	metallization	Nickel (Ni)	7440-02-0						0.068	mg	3688	986
supplier	metallization	Palladium (Pd)	7440-05-3						0.002	mg	108	29
supplier	metallization	Gold (Au)	7440-57-5						0.001	mg	54	14
Die attach	Other inorganic materials	4.410	mg	supplier	glue	Silver (Ag)	7440-22-4		3.528	mg	800000	51130
				supplier	glue	methylene diacrylate	42594-17-2		0.265	mg	60091	3841
				supplier	glue	methacrylate	7534-94-3		0.375	mg	85034	5435
				supplier	glue	Urethane Methacrylate Resin	5888-33-5		0.220	mg	49887	3188
				supplier	glue	Dicumyl peroxide	80-43-3		0.022	mg	4989	319
Bonding wires	Precious metals	0.403	mg	supplier	wire	Gold (Au)	7440-57-5		0.403	mg	1000000	5841
Encapsulation	Other Organic Materials	38.595	mg	supplier	mold compound	Silica, vitreous	60676-86-0		35.739	mg	926001	517957
				supplier	mold compound	epoxy resin	85954-11-6		1.544	mg	40005	22377
				supplier	mold compound	phenol resin	26834-02-6		1.158	mg	30004	16783
				supplier	mold compound	carbon black	1333-86-4		0.154	mg	3990	2232